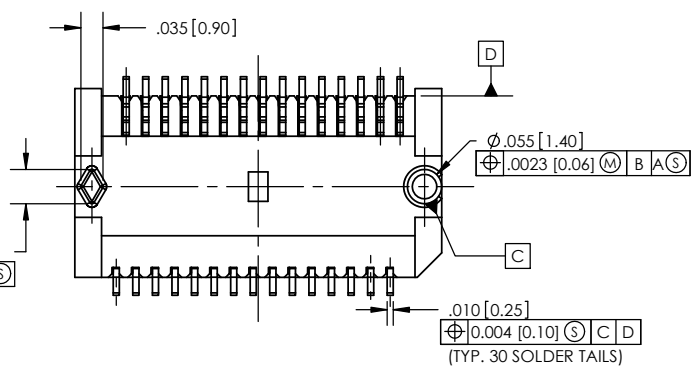
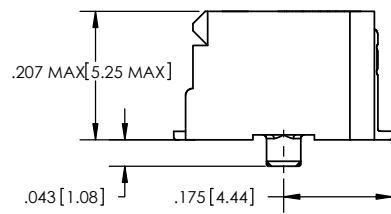
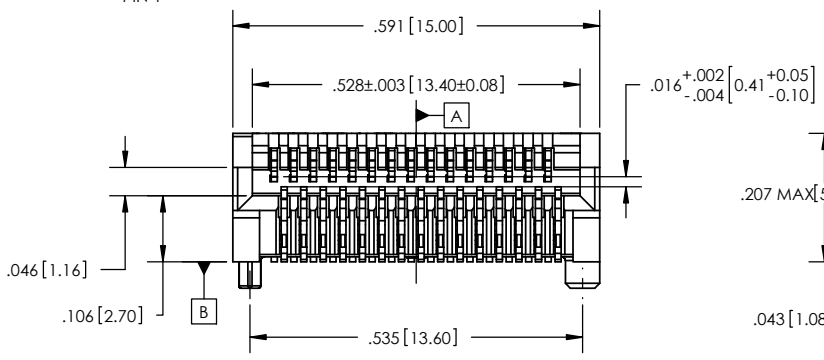
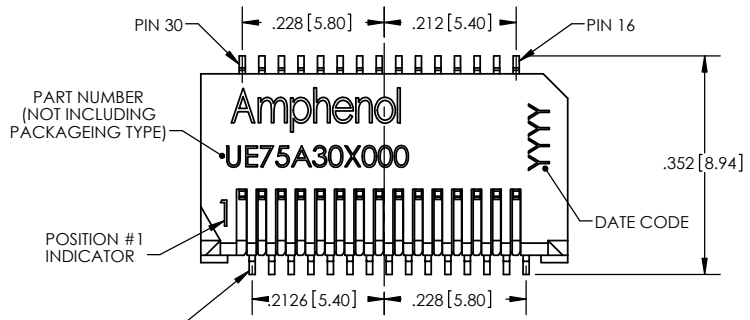


8 7 6 5 4 3 2 1



REVISIONS				
REV.	ZONE	DESCRIPTION	DATE	APPROVED
E		PLATING 5 & 6 ADDED	2007/04/05	A.G
F		MATING END GAP DIM. ADDED	2008/09/03	A.G
G		DRAWING UPDATE	2012/03/21	ZLJ
H		DRAWING UPDATE	2012/10/26	ZLJ

PLASTIC HOUSING:
HIGH TEMPERATURE RESISTANT PLASTIC
COLOUR: BLACK
FLAMABILITY RATING UL94V-0

PACKAGING:
TAPE AND REEL RACKAGING

TEMPERATURE RANGE:
-40°C TO +85°C

MATERIAL NOTES

CONTACTS:
PHOSPHOR BRONZE

PLATING OPTION 2: (RoHS FOR UE75 ONLY)
30µ" [0.76 µm] MIN. GOLD ON MATING AREA AND 2µ" [0.05 µm] GOLD FLASH PLATING ON TERMINATION OVER 50µ" [1.27 µm] MIN. NICKEL UNDER LAYER

PLATING OPTION 3: (RoHS FOR UE75 ONLY)
30µ" [0.76 µm] MIN. GOLD ON MATING AREA AND 100 - 150µ" [3.81 - 7.62 µm] MIN. LOW WHISKER MATTE TIN PLATING ON TERMINATION OVER 50µ" [1.27 µm] MIN. NICKEL UNDER LAYER

PLATING OPTION 5: (RoHS FOR UE75 ONLY)
15µ" [0.38 µm] MIN. GOLD ON MATING AREA AND 2µ" [0.05 µm] GOLD FLASH PLATING ON TERMINATION OVER 50µ" [1.27 µm] MIN. NICKEL UNDER LAYER

PLATING OPTION 6: (RoHS FOR UE75 ONLY)
15µ" [0.38 µm] MIN. GOLD ON MATING AREA AND 100 - 150µ" [3.81 - 7.62 µm] MIN. LOW WHISKER MATTE TIN PLATING ON TERMINATION OVER 50µ" [1.27 µm] MIN. NICKEL UNDER LAYER



AMPHENOL PART NUMBER CONFIGURATION

UE75 - A 30 - X 0 0 0 T

CONTACT PLATING (SEE MATERIAL NOTES)

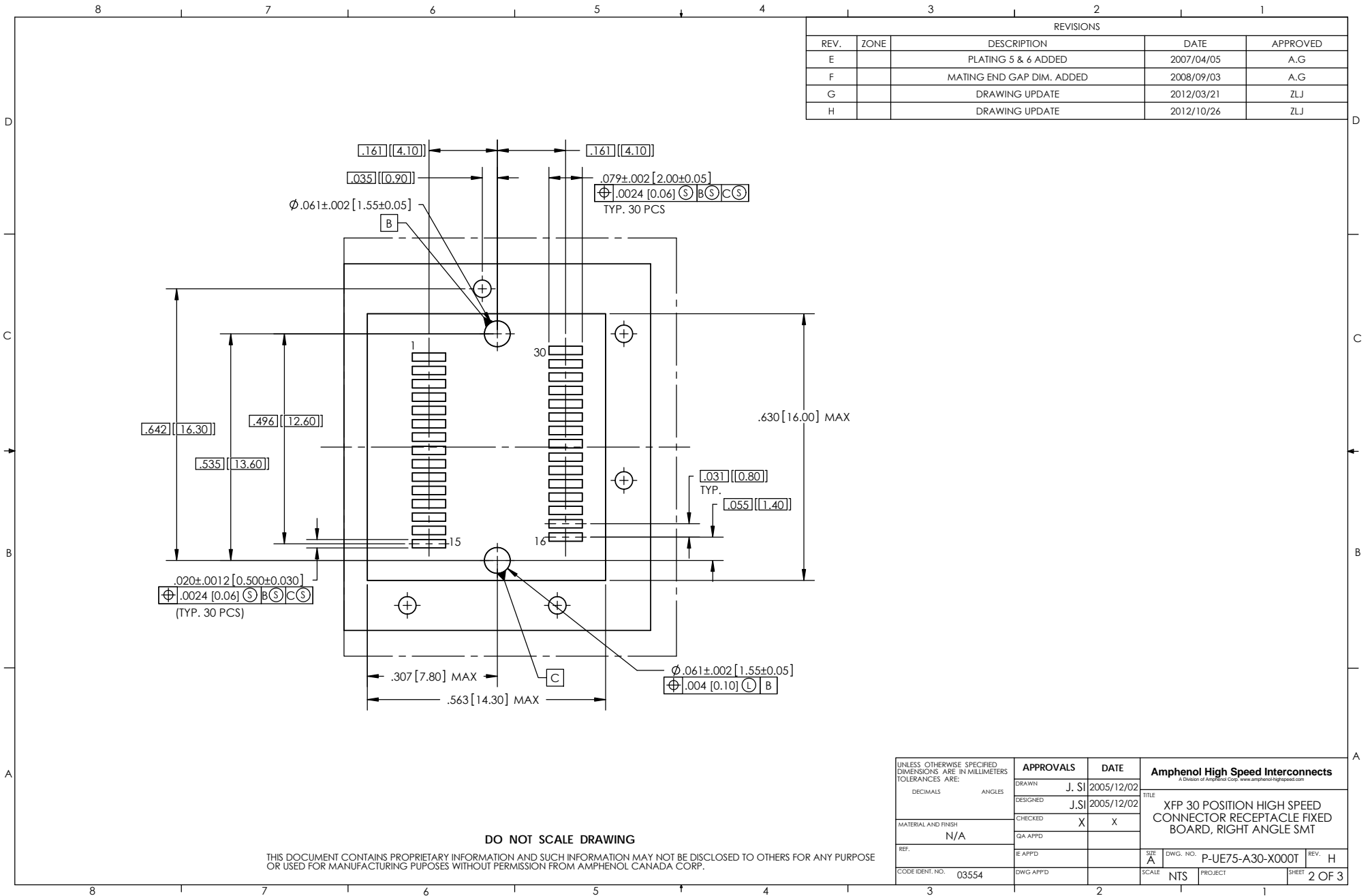
(FOR UE75 RoHS)
2 = PLATING OPTION 2
3 = PLATING OPTION 3
5 = PLATING OPTION 5
6 = PLATING OPTION 6

DO NOT SCALE DRAWING

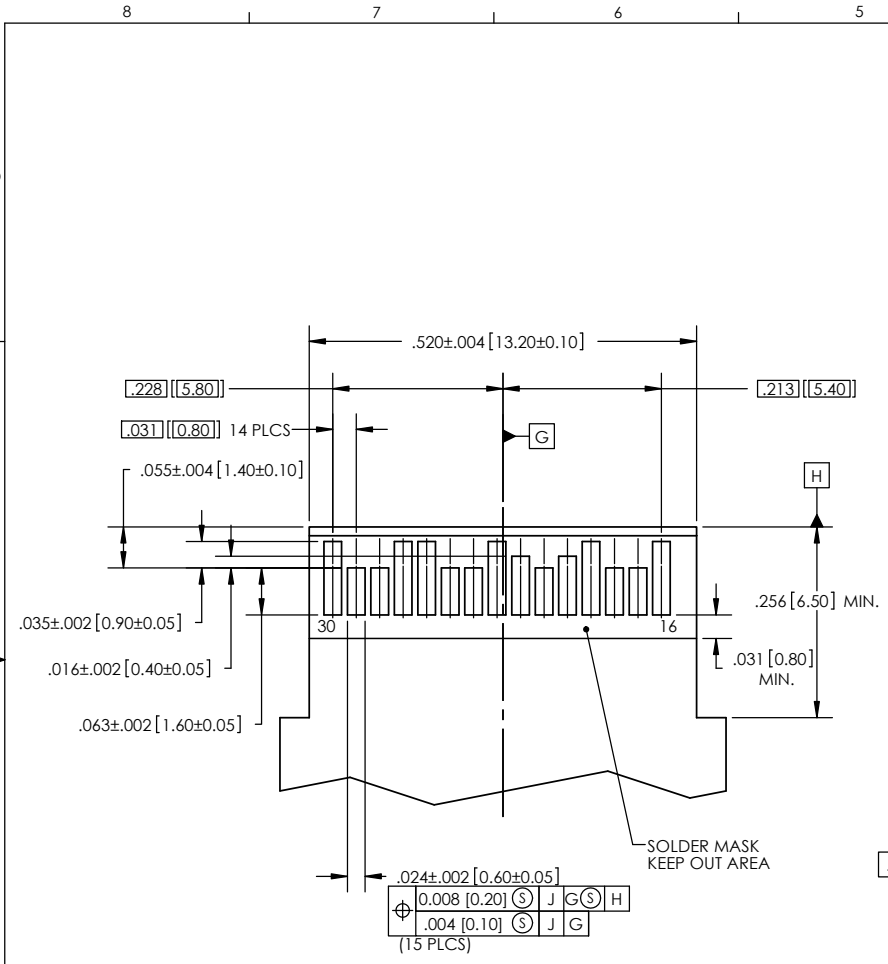
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UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE: DECIMALS ANGLES	APPROVALS	DATE	Amphenol High Speed Interconnects <small>A Division of Amphenol Corp. www.amphenolhighspeed.com</small>	
	DRAWN J.SI	2005/12/02		
	DESIGNED J.SI	2005/12/02	TITLE	XFP 30 POSITION HIGH SPEED CONNECTOR RECEPTACLE FIXED BOARD, RIGHT ANGLE SMT
	CHECKED X	X		
MATERIAL AND FINISH N/A	QA APPD		SIZE A	DWG. NO. P-UE75-A30-X000T
REF.	E APPD		SCALE NTS	PROJECT
CODE IDENT. NO. 03554	DWG APPD		SHEET 1 OF 3	REV. H

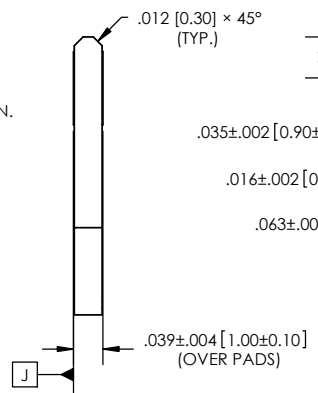
8 7 6 5 4 3 2 1



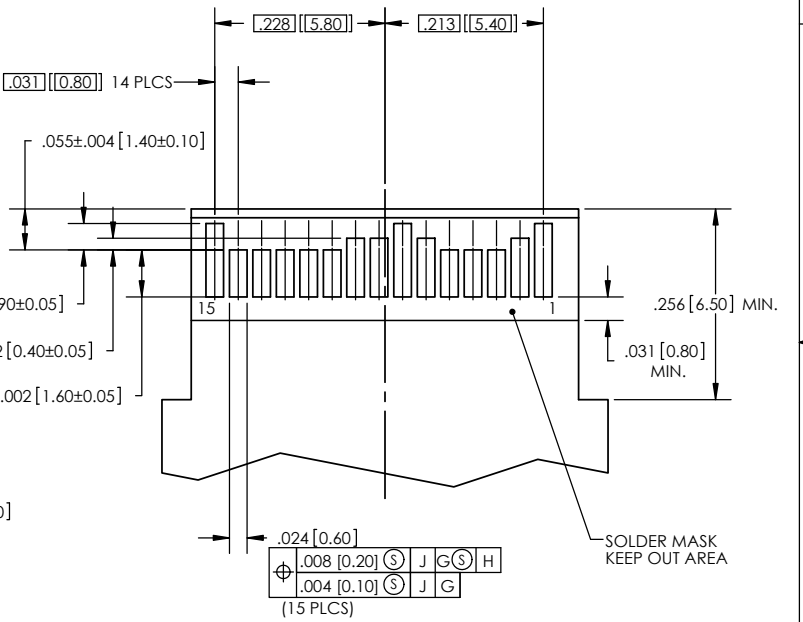
REVISIONS				
REV.	ZONE	DESCRIPTION	DATE	APPROVED
E		PLATING 5 & 6 ADDED	2007/04/05	A.G
F		MATING END GAP DIM. ADDED	2008/09/03	A.G
G		DRAWING UPDATE	2012/03/21	ZLJ
H		DRAWING UPDATE	2012/10/26	ZLJ



TOP VIEW OF BOARD



RECOMMENDED LAYOUT DETAIL
MATING TRANSCEIVER PCB



BOTTOM VIEW OF BOARD

DO NOT SCALE DRAWING

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DECIMALS	ANGLES	DRAWN	J. SI	2005/12/02	TITLE				
		DESIGNED	J. SI	2005/12/02	XFP 30 POSITION HIGH SPEED CONNECTOR RECEPTACLE FIXED BOARD, RIGHT ANGLE SMT				
MATERIAL AND FINISH		CHECKED	X	X					
N/A		QA APPD							
REF.		E APPD			SIZE	DWG. NO.	P-UE75-A30-X000T	REV.	H
CODE IDENT. NO.	03554	DWG APPD			SCALE	NTS	PROJECT	SHEET	3 OF 3

Mouser Electronics

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